FutureHorizons

The Global Semiconductor Industry Analysts

FH MONDAY

9 January 2017

Space-saving chips to usher in slimmer

Thinner smartphones or more space for larger batteries are on the way this year, thanks to a big reduction in the size of the latest mobile processors that power them.

read more

Qualcomm Unveils New SoC at CES

Mobile chip giant Qualcomm announced its 10nm Snapdragon 835 at CES 2017. The new smartphone SoC sports upgrades across all its subsystems that analysts called impressive but evolutionary.

read more

Intel Tips Plans for 5G Modem

Hoping to accelerate its resurgence in mobile, Intel announced plans at CES for a 5G modem for smartphones that will sample in the second half of this year. The x86 giant aims to attract design wins in top 2018 smartphones for the first modem made in its 14 nm process.

read more

FutureHorizons

TALK TO US

Chip Sales Rose Sharply in November

Global semiconductor sales posted a year-to-year sales increase of 7.4% in November 2016 as the chip industry continued to pick up steam headed into the end of the year, according to the Semiconductor Industry Association (SIA) trade group.

read more

EVENTS

Silicon Chip Industry Seminar

– 13 March 2017– London UK

Industry Forecast Briefing

– 17 January 2017 – London UK

DON'T MISS OUT.-
BOOK NOW BY CALLING

+44 1732 740440

OR EMAIL

mail@futurehorizons.com

ZigBee Alliance Offers Universal Language for IoT

PARIS--At CES 2017, the Zigbee Alliance will demonstrate dotdot as a universal language for the IoT, making it possible for smart objects to work together on any network.

read more

Future Horizons Ltd, • 44 Bethel Road • Sevenoaks • Kent TN13 3UE • England
Tel: +44 1732 740440 • Fax: +44 1732 740442
e-mail: mail@futurehorizons.com• http://www.futurehorizons.com/
Affiliates in Europe, India, Israel, Japan, Russian, San Jose California, USA

Space-Saving Chips To Usher In Slimmer Smartphones

Thinner smartphones or more space for larger batteries are on the way this year, thanks to a big reduction in the size of the latest mobile processors that power them.

Qualcomm, the leading mobile chipmaker, said on Tuesday that the new version of its flagship processor— the Snapdragon 835 — would take up about 35 per cent less space than last year's model and consume roughly 25 per cent less power.

Battery life has become mobile users' biggest pain point, as people make ever greater demands of their smartphones.

The latest Qualcomm chip, unveiled at the Consumer Electronics Show (CES) in Las Vegas, has made an unusually big leap in energy efficiency, Keith Kressin, senior vice-president of product management for Snapdragon, told the FT in an interview — using about half the power of similar processors just a few years ago.

Qualcomm Unveils New SoC At CES

LAS VEGAS — Mobile chip giant Qualcomm announced its 10nm Snapdragon 835 at CES 2017. The new smartphone SoC sports upgrades across all its subsystems that analysts called impressive but evolutionary.

The 835 features an upgraded Kyro 280 eight-core CPU, Hexagon 682 DSP, 540 Adreno GPU, Qualcomm Spectra 180 ISP, Quick Charge 4.0, as well as an integrated X16 LTE modem with what Qualcomm calls "gigabit-class LTE connectivity." Overall, it sports a 35% decrease in package size with 25% better power efficiency compared to the existing 821.

Interestingly, the 835 is also the company's first ARM-based processor to support Windows 10 on a mobile device.

"This is big news, with Microsoft adding x86 emulation on ARM to Windows 10," said Kevin Krewell, principal analyst at Tirias Research. "I see this as a real threat to Intel. It may also be a step in Microsoft bringing Windows server to ARM as well," he added.

Intel Tips Plans For 5G Modem

SAN JOSE, Calif. -- Hoping to accelerate its resurgence in mobile, Intel announced plans at CES for a 5G modem for smartphones that will sample in the second half of this year. The x86 giant aims to attract design wins in top 2018 smartphones for the first modem made in its 14 nm process.

The plan is an aggressive effort to be early with a chip that supports 3GPP 5G standards. Engineers attending those meetings say the first phase of the 5G standard won't be formally approved until at least May 2018.

Intel is not alone in the rush to 5G. Its archrival, Qualcomm, announced late last year its X50 5G modem will sample in 2017. It uses eight 100-MHz channels, a 2x2 MIMO antenna array, adaptive beamforming techniques and 64 QAM to achieve a 90dB link budget and works with separate 28 GHz transceiver and power management chips.

Chip Sales Rose Sharply In November

SAN FRANCISCO--Global semiconductor sales posted a year-to-year sales increase of 7.4% in November 2016 as the chip industry continued to pick up steam headed into the end of the year, according to the Semiconductor Industry Association (SIA) trade group.
The November increase was the largest for the semiconductor industry since January 2015, the SIA said.

November's jump in sales increases the likelihood that semiconductor sales for 2016 may have been flat with 2015. After many market watchers--including the SIA--predicted modest declines for semiconductor sales at the beginning of 2016, recent sales data indicates that the industry could achieve sales of about $335 billion, roughly unchanged from 2015

ZigBee Alliance Offers Universal Language For IoT

At CES 2017, the Zigbee Alliance will demonstrate dotdot as a universal language for the IoT, making it possible for smart objects to work together on any network. Members of the zigbee alliance and Thread Group will also showcase the first demonstrations of dotdot devices running over Thread's IP-based networks.

"Dotdot represents the next chapter in the Zigbee Alliance's continued commitment to create and evolve open standards for the smart networks in our homes, businesses and neighborhoods," said Tobin Richardson, Zigbee Alliance president and CEO, in a statement.

"The application layer that is the core language of zigbee devices has driven significant growth in the IoT," Richardson said. "Recognizing the opportunity to multiply that growth for members and the industry, market leaders within the alliance have come together to transform it into a universal language for the IoT, making it available to everyone, everywhere, across their network of choice."